

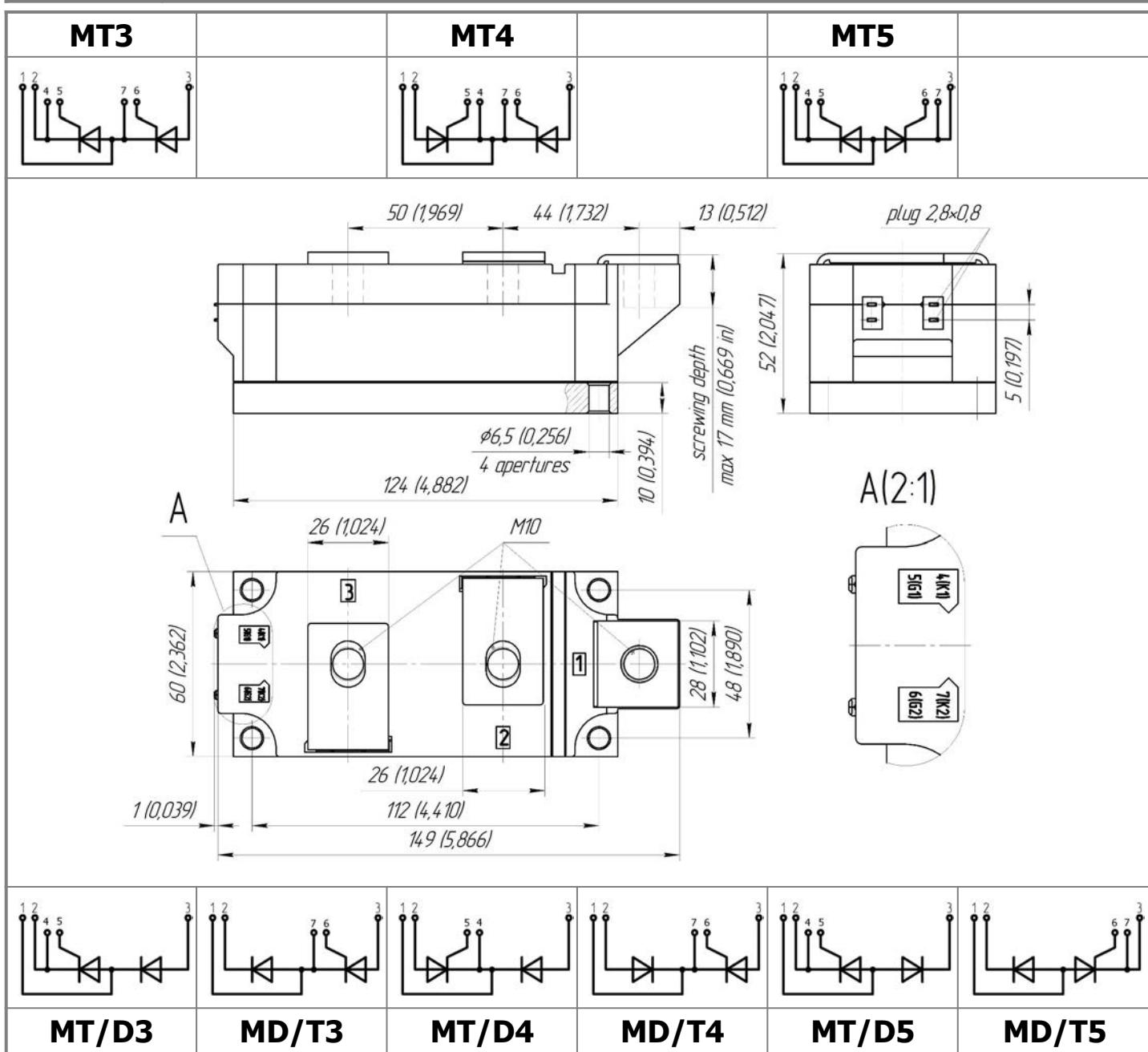


Thyristor Modules

MTx-430-24-A2



Mean on-state current	I _{TAV}	430 A	
Repetitive peak off-state voltage	V _{DRM}	2000...2400 V	
Repetitive peak reverse voltage	V _{RRM}		
Turn-off time	t _q	250 µs	
V _{DRM} , V _{RRM} , V	2000	2200	2400
Voltage code	20	22	24
T _j , °C	-40...+125		



MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Maximum allowable mean on-state current	A	430 458	$T_c=88^\circ\text{C}$; $T_c=85^\circ\text{C}$; 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	675	$T_c=88^\circ\text{C}$; 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	12.0 14.0	$T_j=T_{j \max}$ $T_j=25^\circ\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 1\text{ A}/\mu\text{s}$
			13.0 15.0	$T_j=T_{j \max}$ $T_j=25^\circ\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 1\text{ A}/\mu\text{s}$
I^2t	Safety factor	$\text{A}^2\text{s} \cdot 10^3$	720 980	$T_j=T_{j \max}$ $T_j=25^\circ\text{C}$	180° half-sine wave; $t_p=10\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 1\text{ A}/\mu\text{s}$
			700 930	$T_j=T_{j \max}$ $T_j=25^\circ\text{C}$	180° half-sine wave; $t_p=8.3\text{ ms}$; single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 1\text{ A}/\mu\text{s}$
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2000...2400	$T_{j \min} < T_j < T_{j \max}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2100...2500	$T_{j \min} < T_j < T_{j \max}$; 180° half-sine wave; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.6 \cdot V_{DRM}$ $0.6 \cdot V_{RRM}$	$T_j=T_{j \max}$; Gate open	
TRIGGERING					
I_{FGM}	Peak forward gate current	A	8	$T_j=T_{j \max}$	
V_{RGM}	Peak reverse gate voltage	V	5		
P_G	Gate power dissipation	W	4	$T_j=T_{j \max}$ for DC gate current	
SWITCHING					
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1\text{ Hz}$)	$\text{A}/\mu\text{s}$	1600	$T_j=T_{j \max}$; $V_D=0.67 \cdot V_{DRM}$; $I_{TM}=2100\text{ A}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 2\text{ A}/\mu\text{s}$	
THERMAL					
T_{stg}	Storage temperature	$^\circ\text{C}$	-40...+50		
T_j	Operating junction temperature	$^\circ\text{C}$	-40...+125		
$T_{c op}$	Operating temperature	$^\circ\text{C}$	-40...+125		
MECHANICAL					
a	Acceleration under vibration	m/s^2	50		

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions		
ON-STATE						
V _{TM}	Peak on-state voltage, max	V	1.60	T _j =25 °C; I _{TM} =1256A		
V _{T(TO)}	On-state threshold voltage, max	V	0.989	T _j =T _j max;		
r _T	On-state slope resistance, max	mΩ	0.534	0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}		
I _L	Latching current, max	mA	1000	T _j =25 °C; V _D =12 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs		
I _H	Holding current, max	mA	300	T _j =25 °C; V _D =12 V; Gate open		
BLOCKING						
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	100 3.00	T _j =T _j max T _j = 25 °C	V _D =V _{DRM} ; V _R =V _{RRM}	
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage ¹⁾ , min	V/μs	200, 320, 500, 1000, 1600, 2000, 2500	T _j =T _j max; V _D =0.67·V _{DRM} ; Gate open		
TRIGGERING						
V _{GT}	Gate trigger direct voltage, max	V	3.00 2.50 1.50	T _j = T _j min T _j =25 °C T _j = T _j max	V _D =12 V; I _D =3 A; Direct gate current	
I _{GT}	Gate trigger direct current, max	mA	400 250 150	T _j = T _j min T _j = 25 °C T _j = T _j max		
V _{GD}	Gate non-trigger direct voltage, min	V	0.55	T _j =T _j max; V _D =0.67·V _{DRM} ;	Direct gate current	
I _{GD}	Gate non-trigger direct current, min	mA	60.00	Direct gate current		
SWITCHING						
t _{gd}	Delay time, max	μs	1.25	T _j =25 °C; V _D =1000 V; I _{TM} =I _{TAV} ; di/dt=200 A/μs;	Gate pulse: I _G =2 A; V _G =20 V; t _{GP} =50 μs; di _G /dt=2 A/μs	
t _{gt}	Turn-on time, max	μs	8.00			
t _q	Turn-off time ²⁾ , max	μs	250	dv _D /dt=50 V/μs; T _j =T _j max; I _{TM} = I _{TAV} ; di _R /dt=10 A/μs; V _R =100V; V _D =0.67 V _{DRM} ;	DC	
Q _{rr}	Recovered charge, max	μC	1540	T _j =T _j max; I _{TM} =I _{TAV} ;		
t _{rr}	Reverse recovery time, max	μs	24	di _R /dt=-10 A/μs;	V _R =100 V	
I _{rr}	Reverse recovery current, max	A	128			
THERMAL						
R _{thjc}	Thermal resistance, junction to case				180° half-sine wave, 50 Hz	
	per module	°C/W	0.0275			
	per arm	°C/W	0.0550			
	per module	°C/W	0.0265			
	per arm	°C/W	0.0530			
R _{thch}	Thermal resistance, case to heatsink				DC	
	per module	°C/W	0.0100			
	per arm	°C/W	0.0200			
INSULATION						
V _{ISOL}	Insulation test voltage	kV	3.00	Sine wave, 50 Hz;	t=60 sec	
			3.60	RMS		
MECHANICAL						
M ₁	Mounting torque (M6) ³⁾	Nm	6.00	Tolerance ± 15%		
M ₂	Terminal connection torque (M10) ³⁾	Nm	12.00	Tolerance ± 15%		
m	Weight, max	g	1500			

PART NUMBERING GUIDE								NOTES																							
MT	3	-	430	-	24	-	A2	M2	-	A2	-	N																			
1	2		3		4		5	6		7		8																			
1. Thyristor module (MT)								1) Critical rate of rise of off-state voltage																							
Thyristor – Diode module (MT/D)								<table border="1"> <tr> <td>Symbol of Group (dv_D/dt)_{crit}, V/μs</td><td>P2</td><td>K2</td><td>E2</td><td>A2</td><td>T1</td><td>P1</td><td>M1</td></tr> <tr> <td>200</td><td>320</td><td>500</td><td>1000</td><td>1600</td><td>2000</td><td>2500</td><td></td></tr> </table>								Symbol of Group (dv _D /dt) _{crit} , V/μs	P2	K2	E2	A2	T1	P1	M1	200	320	500	1000	1600	2000	2500	
Symbol of Group (dv _D /dt) _{crit} , V/μs	P2	K2	E2	A2	T1	P1	M1																								
200	320	500	1000	1600	2000	2500																									
Diode – Thyristor module (MD/T)								2) Turn-off time (dv _D /dt=50 V/μs)																							
2. Circuit Schematic:								<table border="1"> <tr> <td>Symbol of Group t_q, μs</td><td>M2</td></tr> <tr> <td></td><td>250</td></tr> </table>							Symbol of Group t _q , μs	M2		250													
Symbol of Group t _q , μs	M2																														
	250																														
3. 3 – serial connection								3) The screws must be lubricated																							
4. 4 – common Cathode																															
5. 5 – common Anode																															
6. 6. Average On-state Current, A																															
7. 7. Voltage Code																															
8. 8. Critical rate of rise of off-state voltage																															
9. 9. Group of turn-off time (dv _D /dt=50 V/μs)																															
10. 10. Package Type (M.A2)																															
11. 11. Ambient Conditions:																															
N – Normal																															

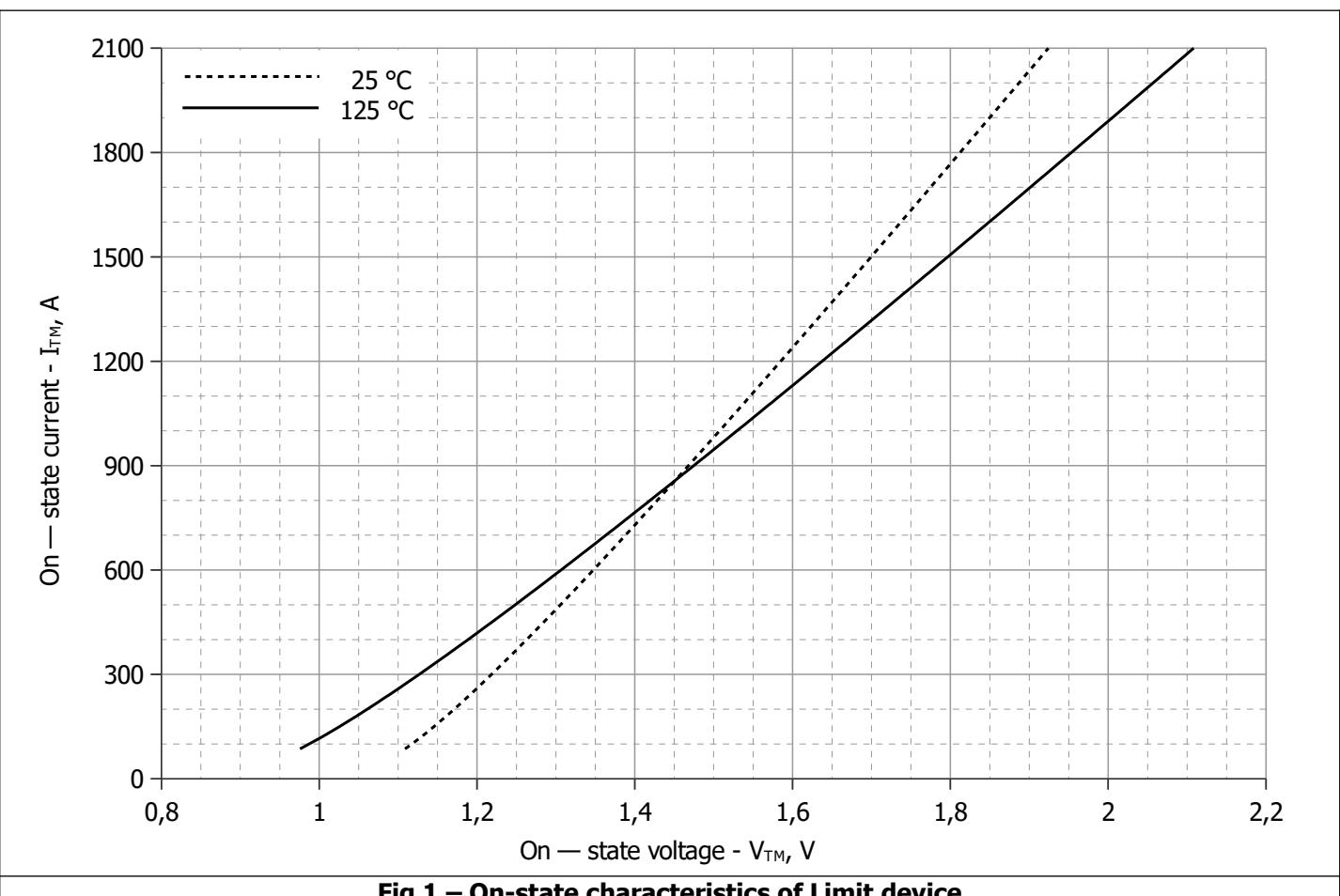


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_j = 25^\circ C$	$T_j = T_{j,\max}$
A	0.99632746	0.84110408
B	0.00033561	0.00045473
C	0.01319285	0.01105644
D	0.00266446	0.00497025

On-state characteristic model (see Fig. 1)

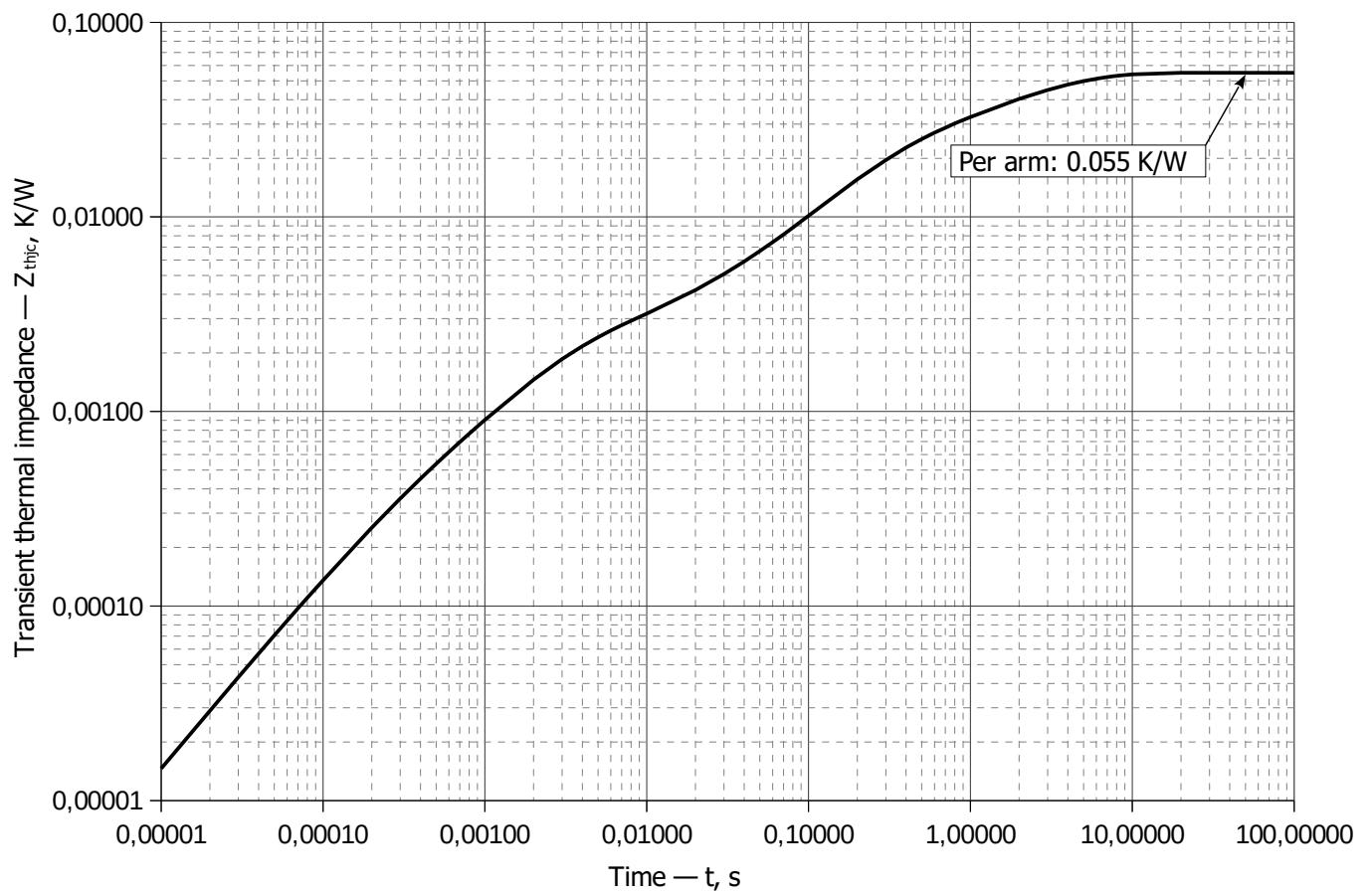


Fig 2 – Transient thermal impedance Z_{thjc} vs. time t

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

i	1	2	3	4	5	6
R_i , K/W	0.0249	0.0112	0.01635	0.0006528	0.001791	0.0001363
τ_i , s	3.132	1.000	0.2335	0.01038	0.002348	0.0002448

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

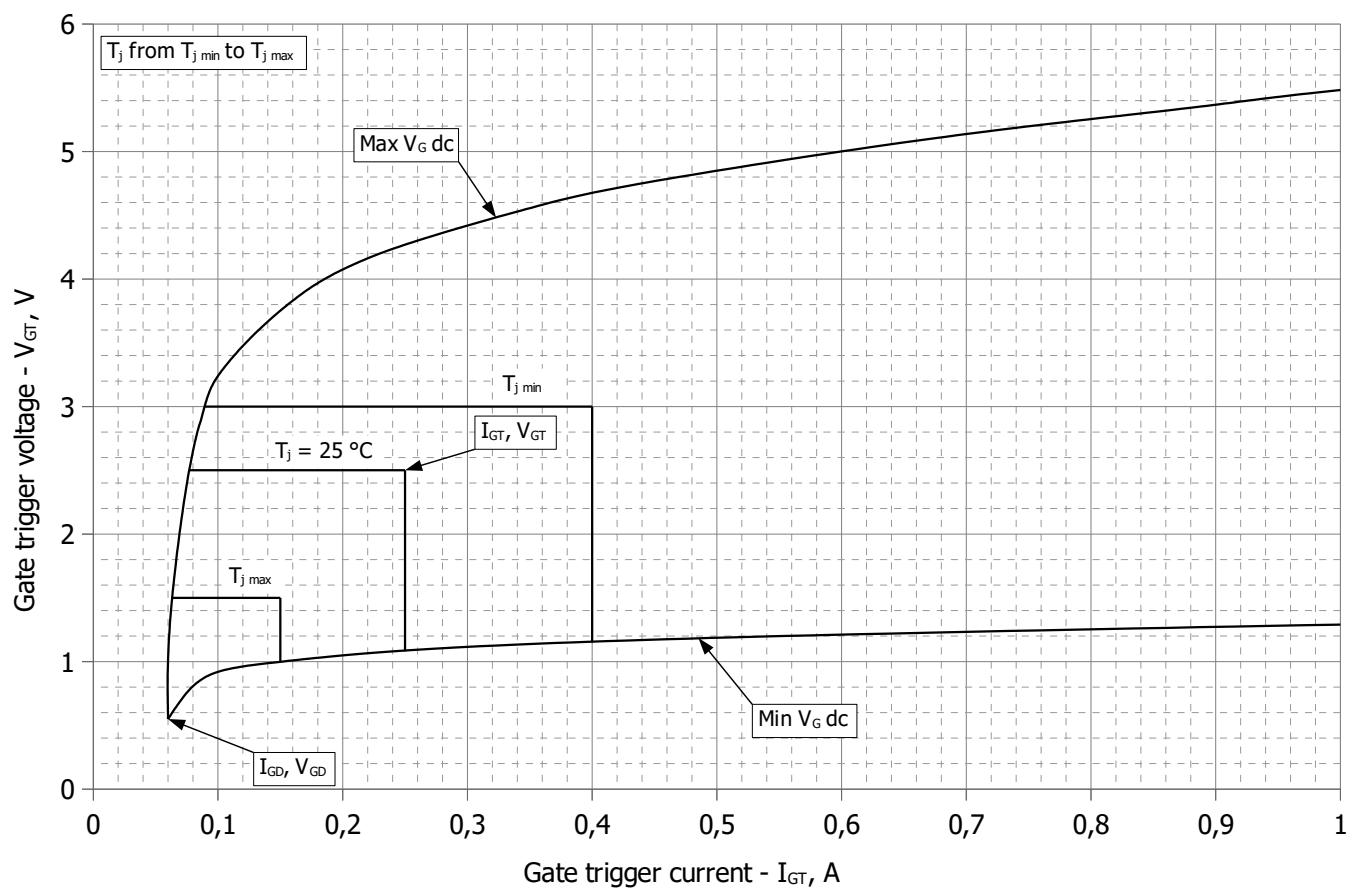


Fig 3 – Gate characteristics – Trigger limits

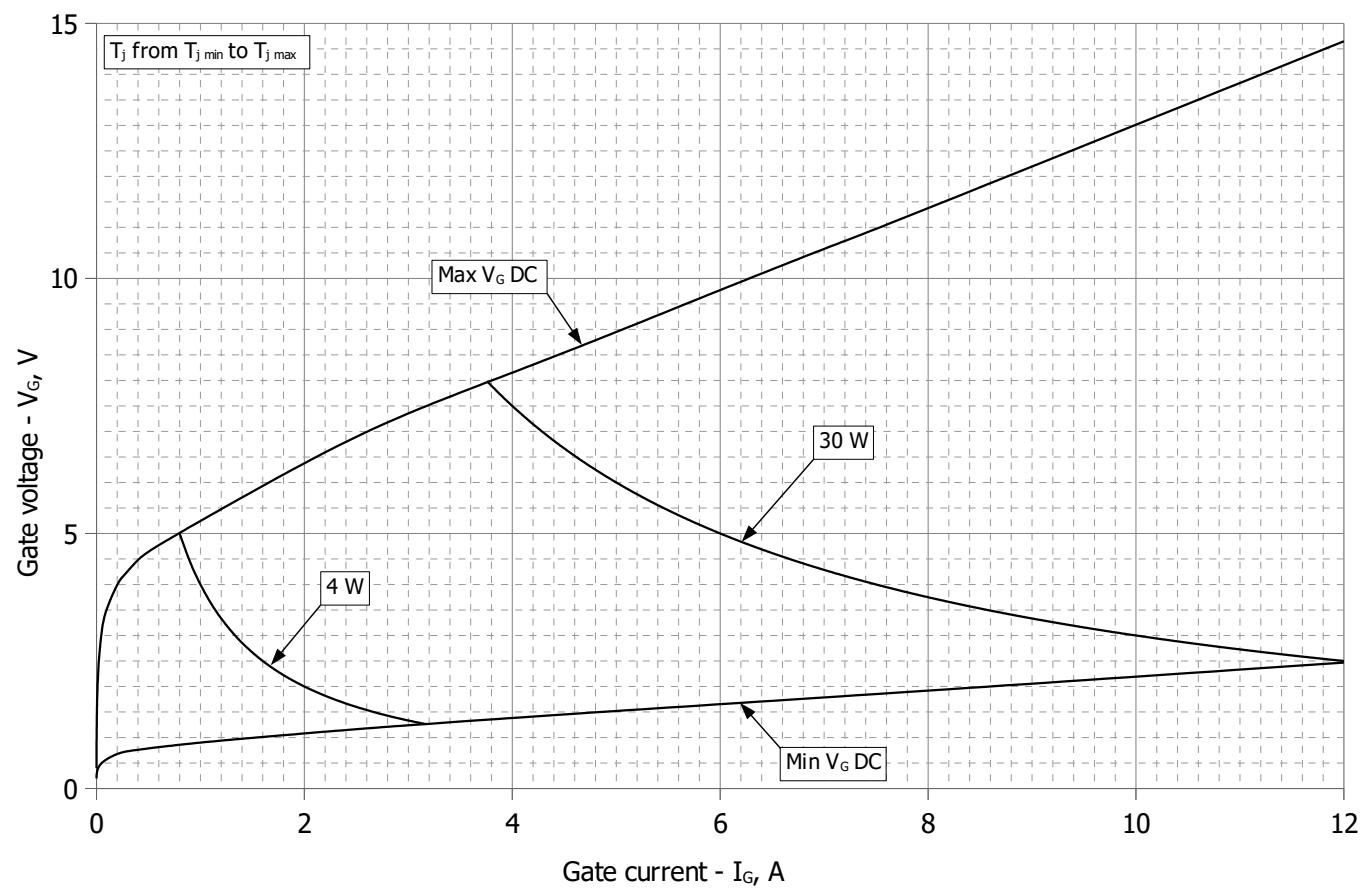


Fig 4 - Gate characteristics – Power curves

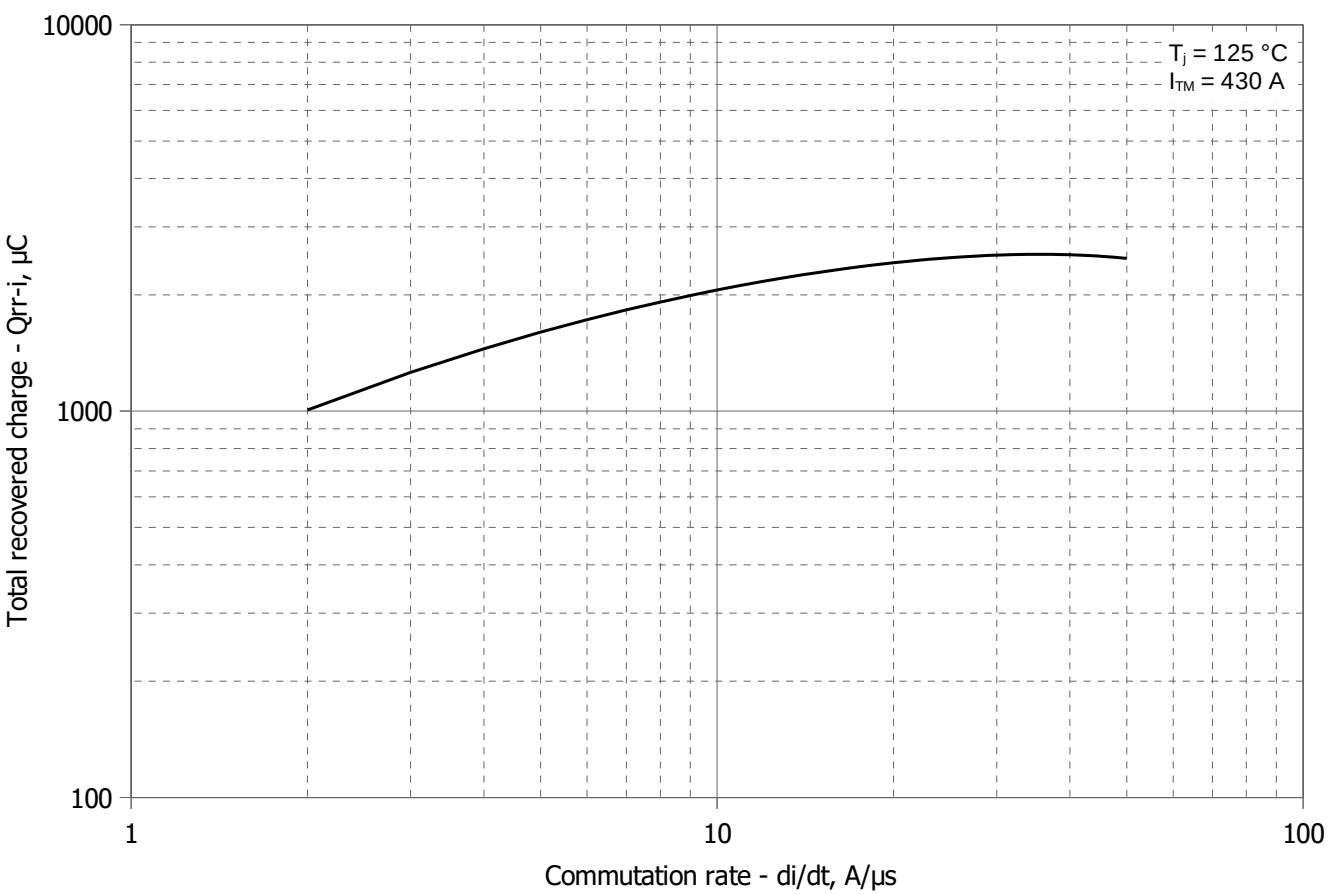


Fig 5 – Maximum recovered charge Q_{rr-i} (integral) vs. commutation rate di_R/dt

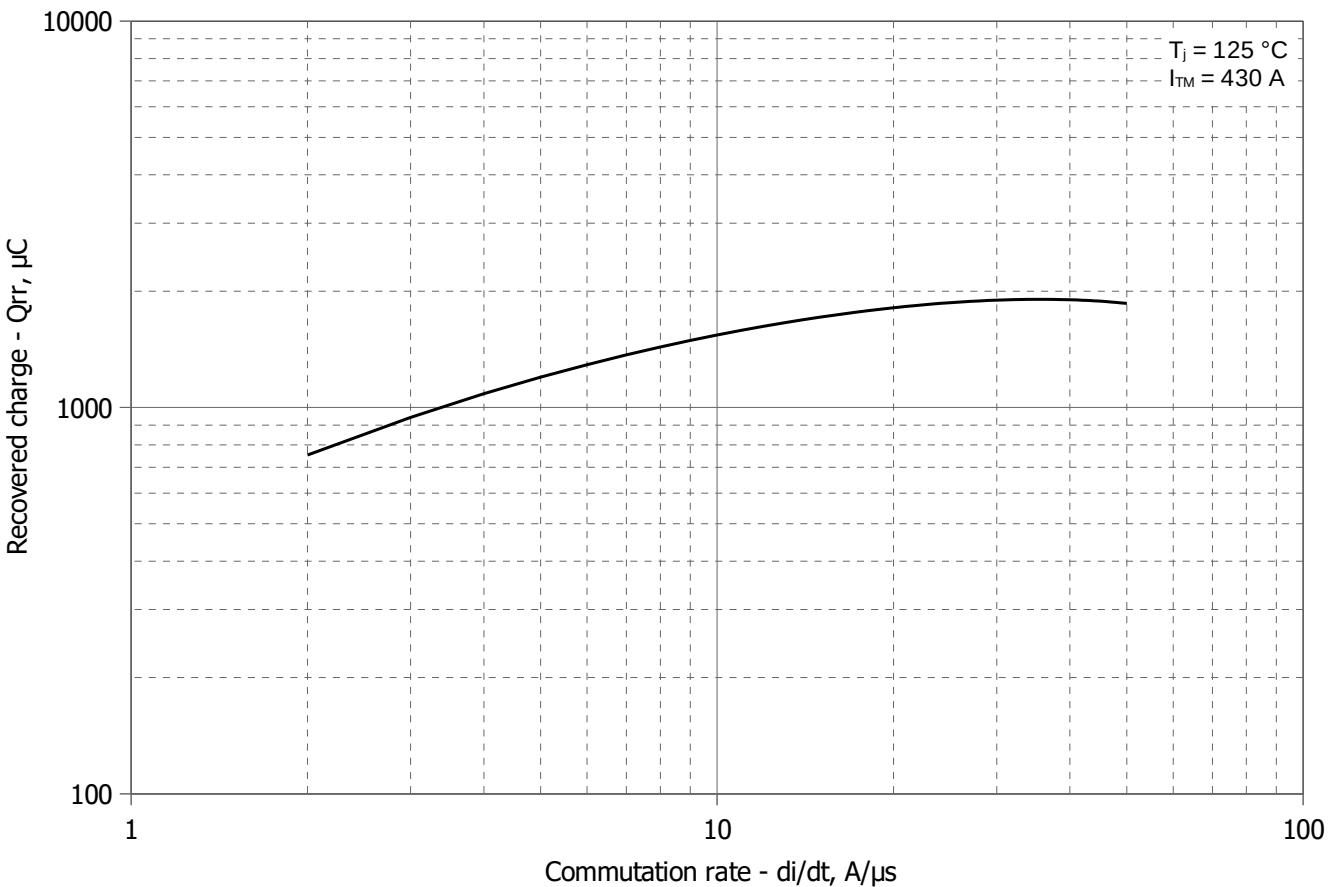


Fig 6 – Maximum recovered charge Q_{rr} vs. commutation rate di_R/dt (25% chord)

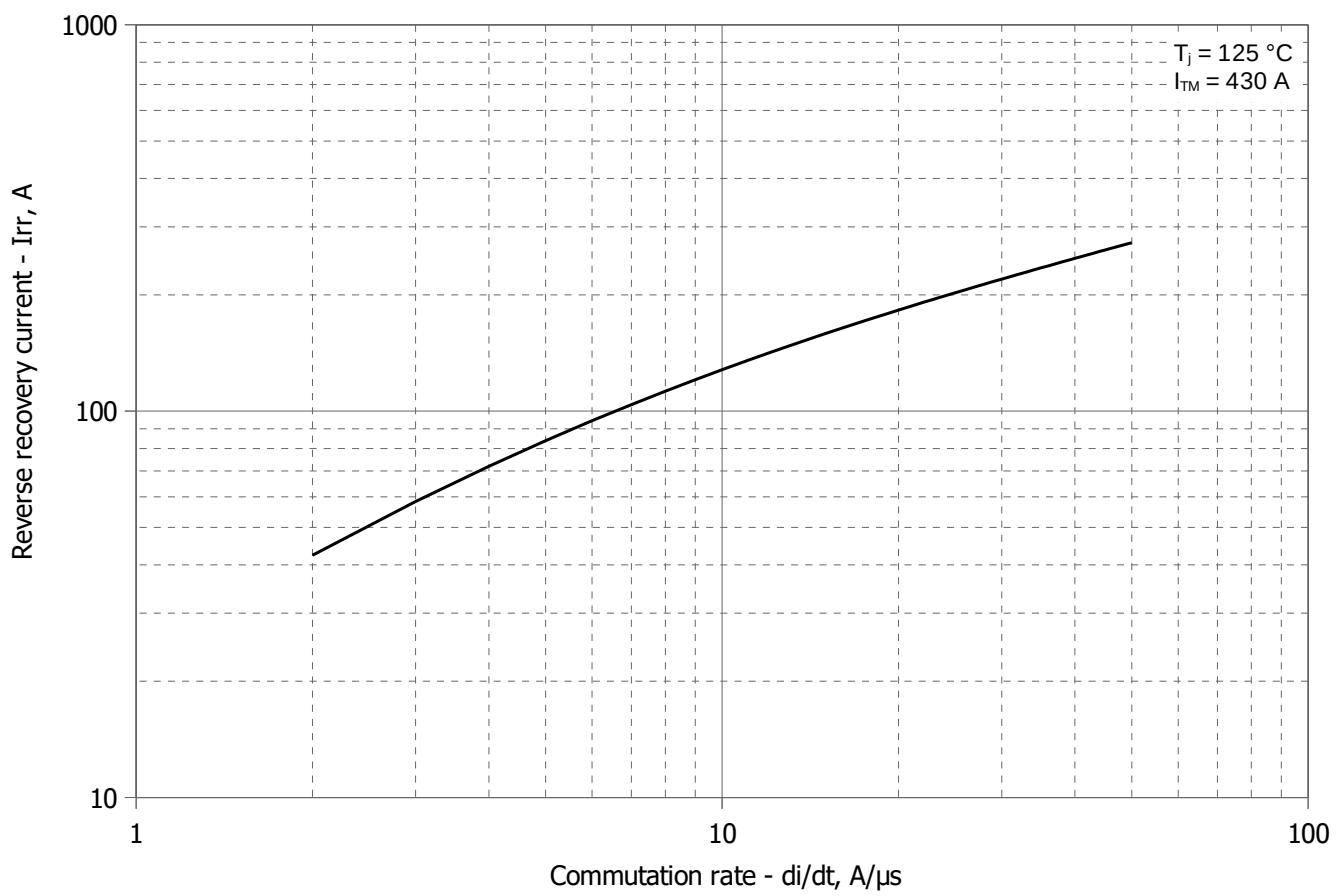


Fig 7 – Maximum reverse recovery current I_{rr} vs. commutation rate di_r/dt

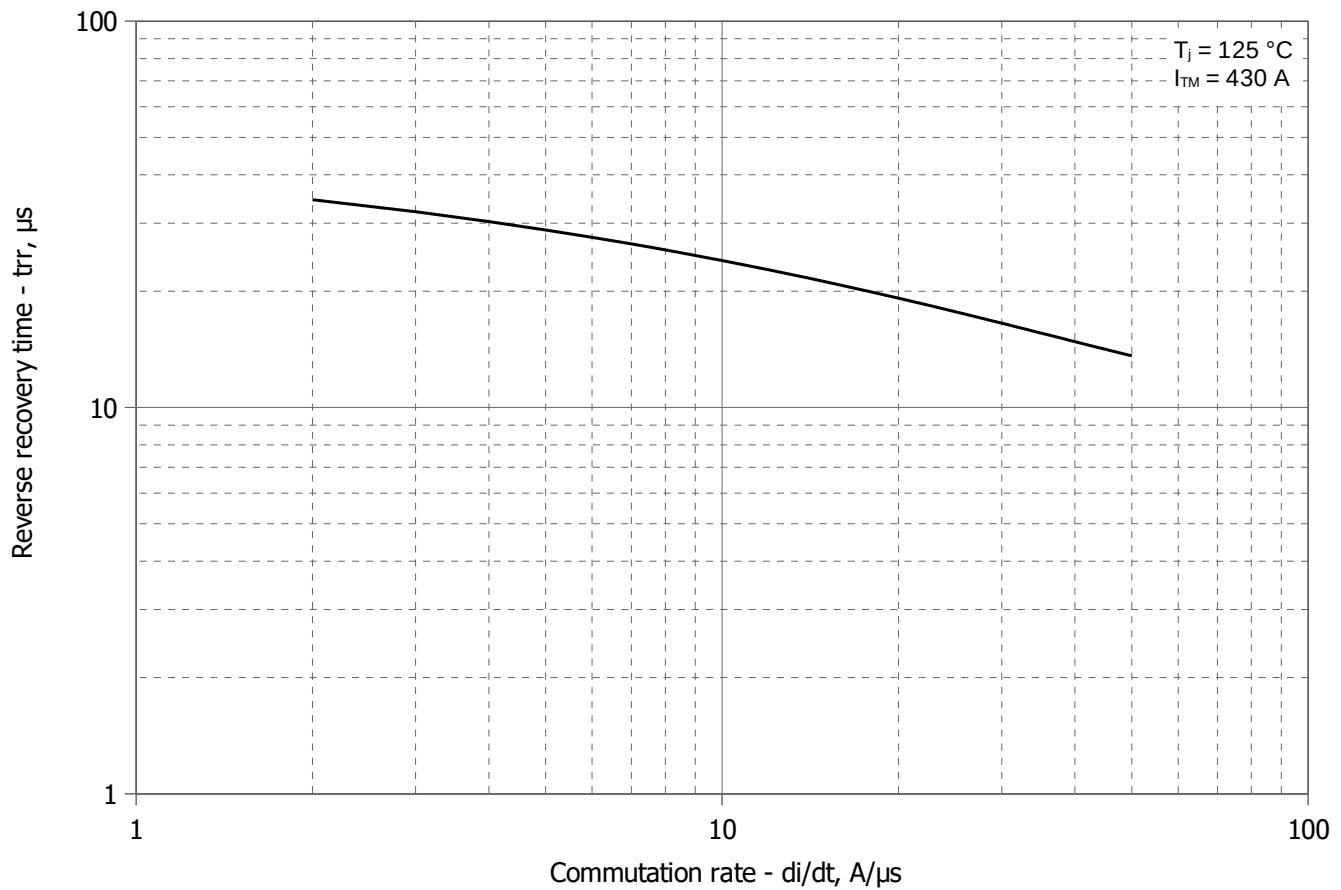


Fig 8 – Maximum recovery time t_{rr} vs. commutation rate di_r/dt (25% chord)

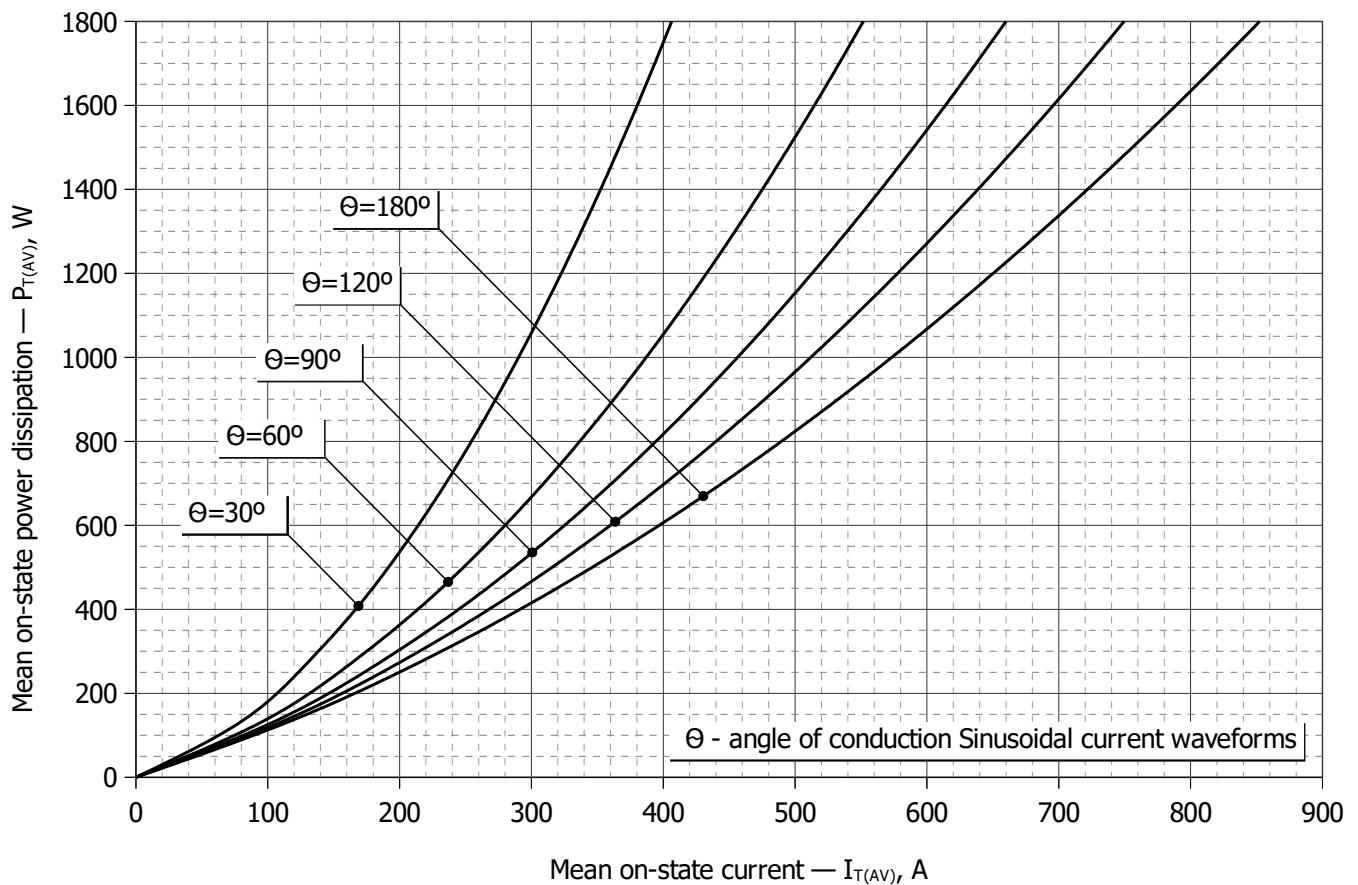


Fig. 9 - Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for sinusoidal current waveforms at different conduction angles ($f=50\text{Hz}$)

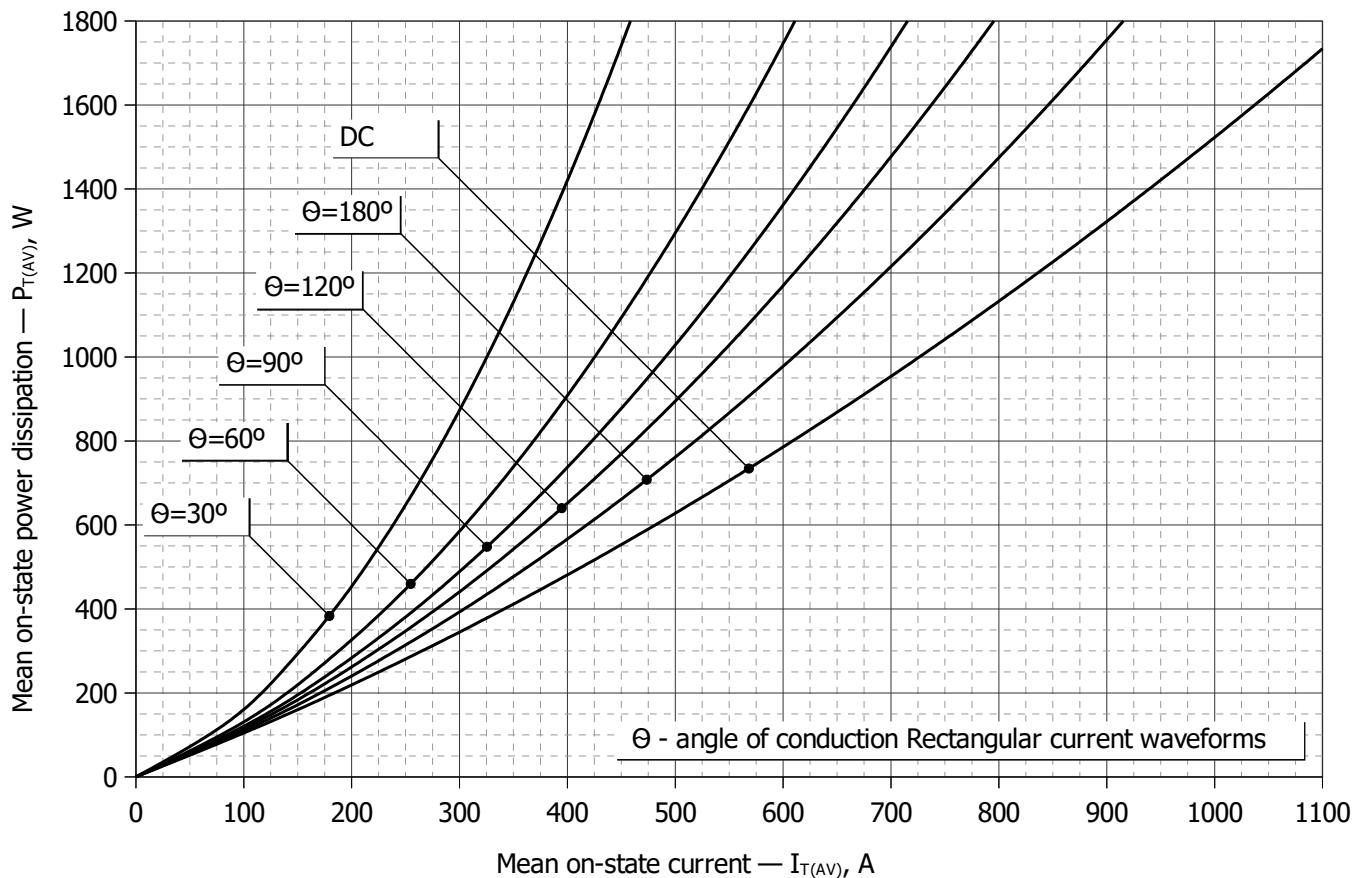


Fig. 10 – Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for rectangular current waveforms at different conduction angles and for DC ($f=50\text{Hz}$)

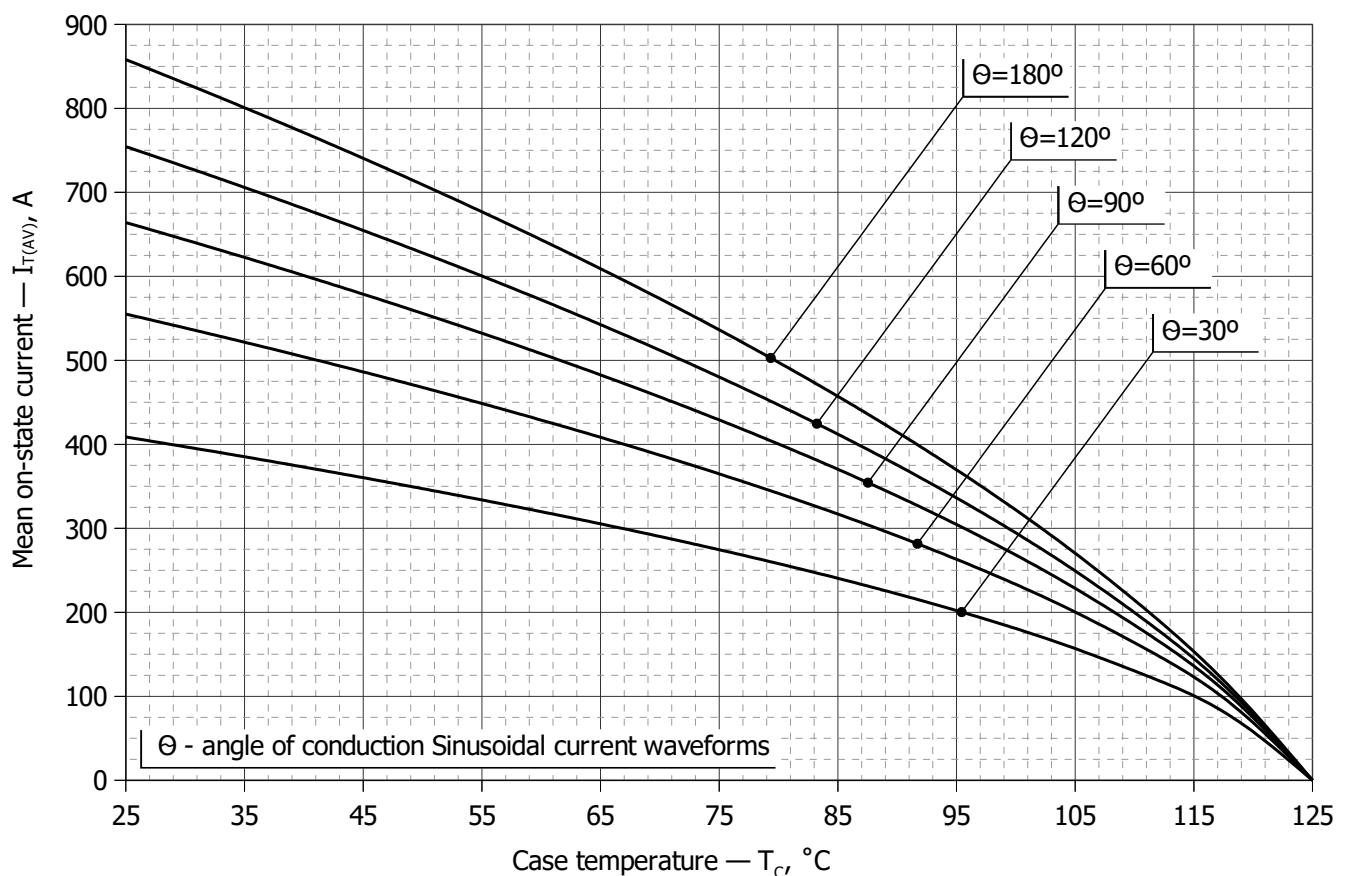


Fig. 11 – Mean on-state current I_{TAV} vs. case temperature T_c for sinusoidal current waveforms at different conduction angles ($f=50\text{Hz}$)

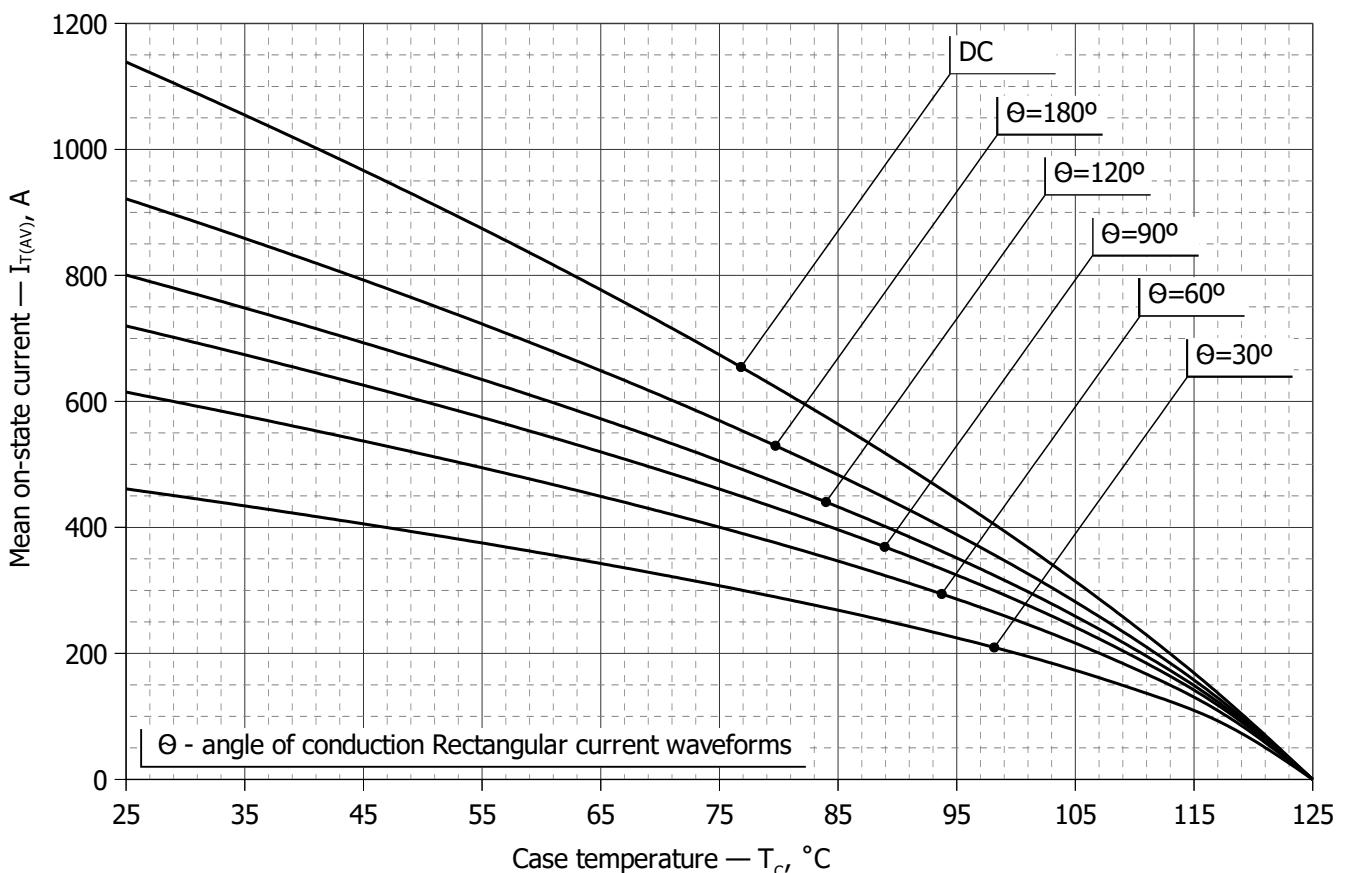


Fig. 12 - Mean on-state current I_{TAV} vs. case temperature T_c for rectangular current waveforms at different conduction angles and for DC ($f=50\text{Hz}$)

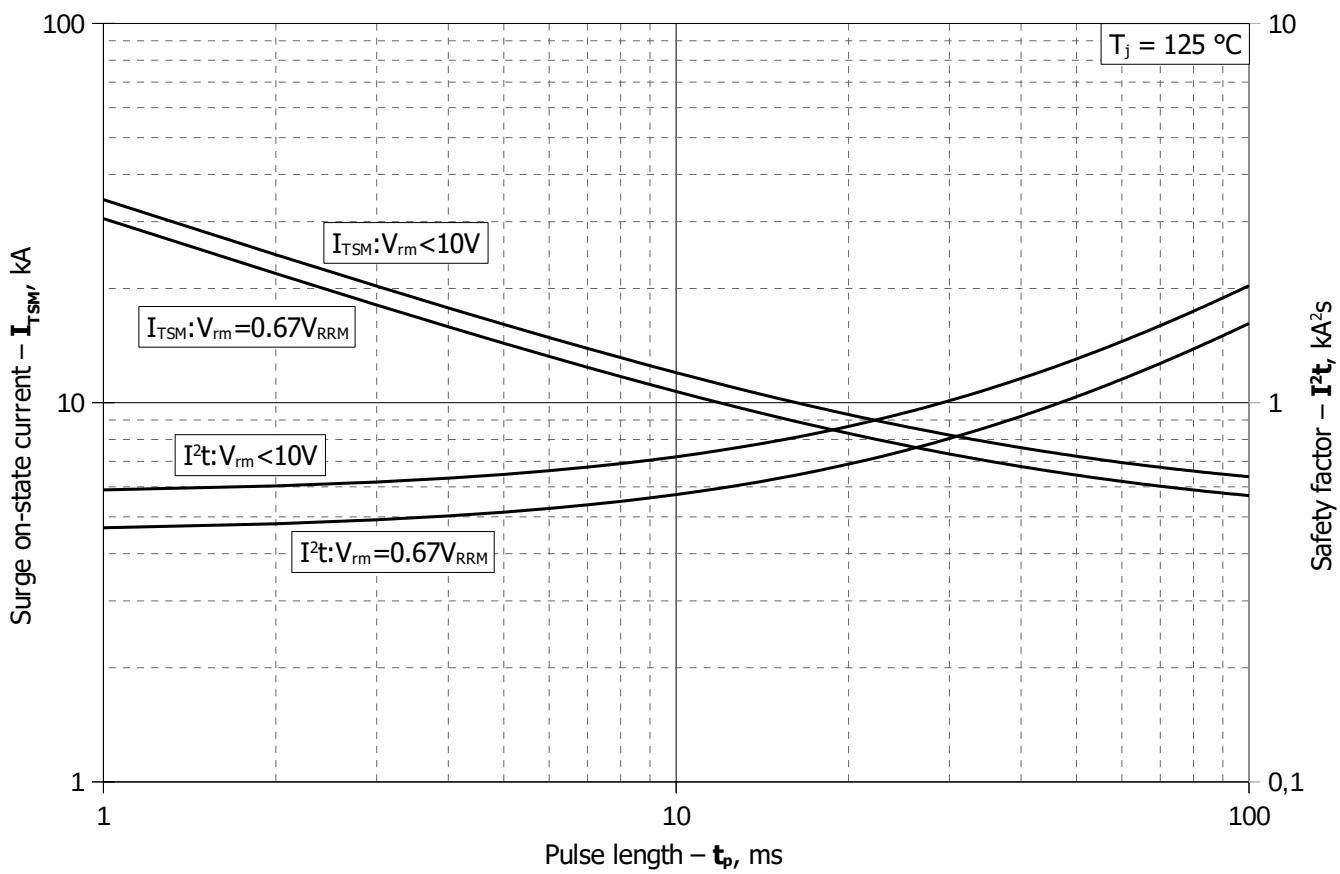


Fig. 13 – Maximum surge on-state current I_{TSM} and safety factor I^2t vs. pulse length t_p

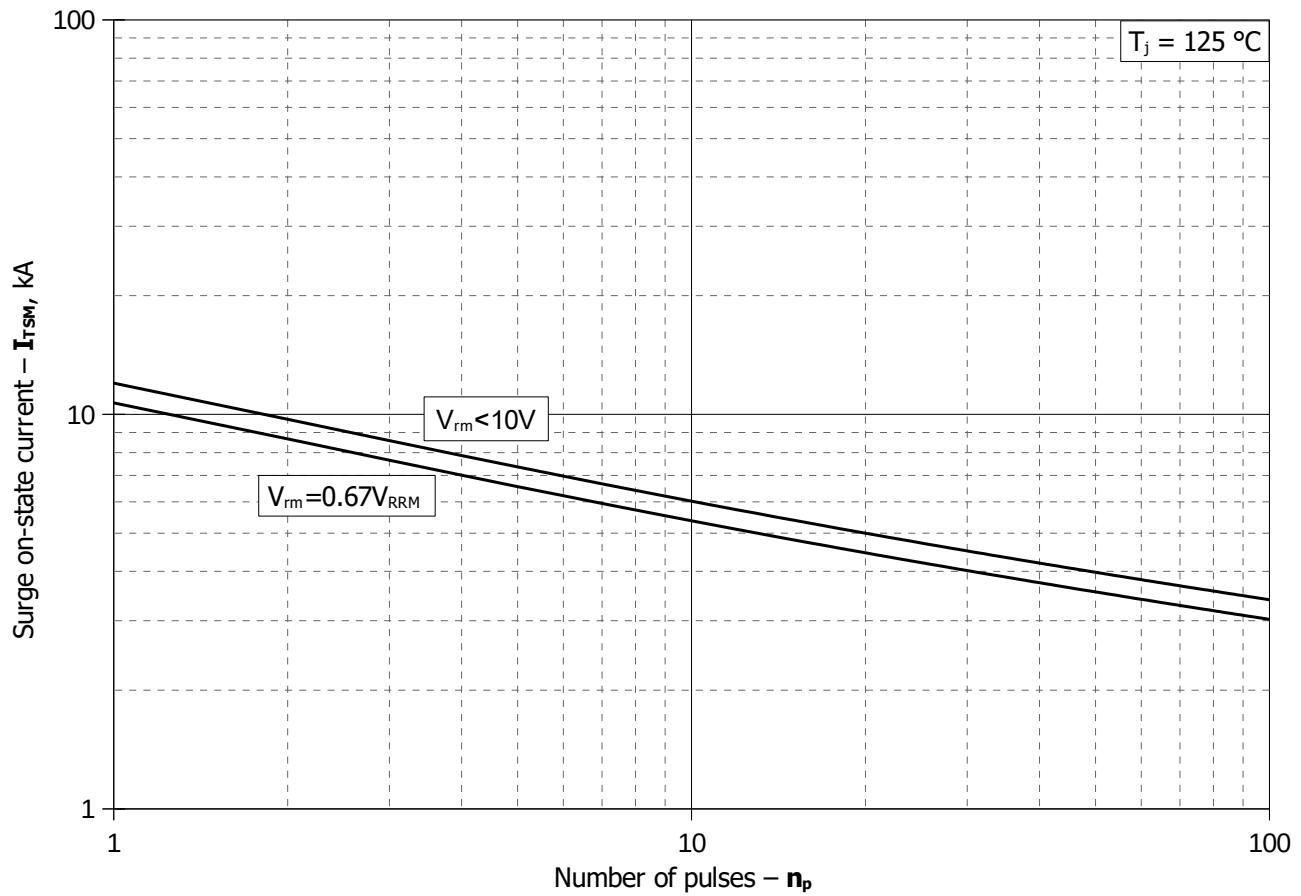


Fig. 14 - Maximum surge on-state current I_{TSM} vs. number of pulses n_p